



Fact Sheet



Delivering Innovation across Mobile Devices, PCs, Software and Services

April 3, 2014 – In keynote presentations made today at the [Intel Developer Forum](#) in Shenzhen, China, Intel Corporation executives [Doug Fisher](#), [Hermann Eul](#) and [Kirk Skaugen](#) articulated the opportunities for collaboration and innovation between the company and the growing technology ecosystem in Shenzhen and broader China.

Aggressive Innovation in Personal Computing

As the No. 1 PC market in the world, Skaugen, senior vice president and general manager of Intel's PC Client Group, offered his appreciation and support for the China technology ecosystem and the greater China PC developers. To continue to accelerate PC growth in China, Skaugen said the company will focus on three key areas: product innovation, segmentation and cost reduction, and delivering new experiences on Intel platforms.

In the product innovation space, Skaugen highlighted and demonstrated several new devices including SKUs from CZC, THD, Jumper and Lengda as well as a new QVOD* media box.

Wang Xin, CEO of QVOD, joined Skaugen on stage to discuss the company's effort to deliver anytime, anywhere, interactive entertainment. The QVOD media box, available later this year, is based on Intel's current "Bay Trail" processors and the two companies are exploring additional collaborations.

Skaugen said Intel's cost-reduction efforts include the elimination of over 500 board components that will bring bill of material (BOM) costs down on value and entry-level PCs based on Bay Trail processors.

In a brief preview of Intel's future roadmap for PCs and mobile devices, Skaugen said the effort to bring innovation to the value space will continue in earnest with the next-generation 14nm SoC, code-named Braswell. He also highlighted Intel's next-generation 5th gen Intel® Core™ processors, formerly code-named Broadwell, as the company's first products on its leading 14nm manufacturing technology. Available to customers later this year, this next-generation platform will offer increased performance of [Intel® Iris™](#) graphics and enable devices across the spectrum of personal computing, ranging from low-power 2 in 1 fanless devices to high-performance enthusiast gaming systems.

To drive simpler technology with more natural and immersive experiences, Intel, in collaboration with China-based companies including Tencent and iFlyTek, will bring new capabilities to Intel-based devices through enhanced video conferencing and an integrated voice experience. Skaugen also highlighted that Intel is working with Xiaomi on a future [Intel® Widi](#) enabled set top box. During an onstage wireless charging demo, Skaugen asked the technology community to come together with the Alliance for Wireless Power (A4WP) to jointly deliver on the goal of eliminating wires.

Accelerated Mobile Roadmap

Eul, vice president and general manager of Intel's Mobile and Communications Group, demonstrated how Intel is accelerating innovation across its mobile platforms, from Intel® Atom™ to LTE, to scale at all prices and designs. The company continues to partner with emerging ODMs and OEMs in China and Taiwan to innovate and drive costs down to deliver compelling mobile devices to consumers around the globe. The China technology ecosystem is key to Intel's goal of increasing sales of Intel-based tablets this year, and the company has an established program to help these ODMs and OEMs develop, market and sell Intel-based mobile devices at scale.

To further fuel the availability of low-cost, Intel-based tablets, Eul outlined how the company is expanding its Intel® Atom™ Z3700 series ("Bay Trail") processor lineup to include several new products. New entry SKUs deliver 64-bit-ready, quad-core performance at a much lower cost based on engineering changes to the board design and other third-party components. Eul said these entry "Bay Trail" SKUs are currently in production and Intel anticipates OEMs to launch both Windows* and Android* devices this summer, with some starting at prices as low as US\$99.

Intel is also introducing two tablet master reference designs that will be available this summer. The reference designs help ODMs deliver low-cost, high-quality Intel-based tablets faster.

Eul also disclosed more details about Intel's future SoFIA 3G product, a dual-chip, fully integrated SoC that will begin shipping in the fourth quarter this year. SoFIA builds on Intel's proven communications platforms by adding powerful Intel Atom cores, and it will be targeted at entry and value smartphones and tablets.

Eul said LTE is a priority and opportunity for Intel. The company's 2014 LTE platform (Intel® XMM™ 7260) features five-mode support, including support for TD-LTE, and TD-SCDMA, which expands its addressable market to include China. Eul said the company is already actively engaged with China operators for certification and field trials are underway.

Delivering Great Experiences on Intel Architecture for Developers, End Users through Software and Services

In an effort to deliver great user experiences to consumers and business users, Intel is committed to providing the best tools and environments for all developers – from device developers to software engineers. Fisher, vice president and general manager of Intel's Software and Services Group, showcased how Intel's core competencies in both Android and Windows aim to provide the best experience for Intel® Architecture (IA) across audiences, devices and operating systems.

Fisher highlighted Intel's increased focus on Android developers to help improve the quality of their services and products, accelerate and scale their businesses, and unlock opportunities in the burgeoning mobile industry. He also highlighted the company's effort to advance security in Intel-based Android mobile devices and provide a dynamic experience for Android and Windows applications.

Intel's broadening focus on Android includes a new, comprehensive device developer program that will be rolled out over the next few months. As part of the program, a [device developer resource portal](#) is available today as a one-stop shop for all Intel resources, including source code, documents and specs for Android on IA. Intel Build Tool Suite for Android will also be available in the coming months to automate the configuration and customization of

firmware and operating system images for new devices. Local resources such as builder training events, local support teams for developers and academic programs to train tomorrow's designers are offered through the program.

Intel also released Android KitKat 4.4 with a 64-bit kernel optimized for IA. With this release, the company ported, validated and tested the Android Open Source code on IA, taking on the work that developers typically would need to do on their own. This release will provide the ecosystem with 64-bit kernel support for development of next-generation devices. Fisher said Intel will regularly make Android code for IA available as part of the company's effort to speed up the device development process and improve quality.

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